

### Key Features

- ◆ Laser-Configured ASIC (LASIC™) technology offers the ultimate combination of performance, flexibility, and low cost
- ◆ Functionally, architecturally, and electrically compatible with industry-standard FLEX® 8000A™ series FPGAs
- ◆ High Density
  - 12,000 Usable gates
  - 1,188 Flip-flops
  - 184 Maximum user I/O pins
- ◆ Laser fuse technology provides very fast, dense interconnect routing
- ◆ Optional Instant-On configuration eliminates the need for an external configuration EPROM
- ◆ Fabricated using 0.5 micron CMOS process
- ◆ Very low current consumption (active and standby)
- ◆ 3.3 volt or 5.0 volt operation
- ◆ Alpha particle immune

### CL8000 Product Family Overview

Parameter	CL8282A CL8282AV	CL8452A	CL8636A	CL8820A	CL81188A	CL81500A
Available Gates	5,000	8,000	12,000	16,000	24,000	32,000
Useable Gates	2,500	4,000	6,000	8,000	12,000	16,000
Flip-flops	282	452	636	820	1,188	1,500
Logic Elements	208	336	504	672	1,008	1,296
Max user I/O pins	78	120	136	152	184	298
Packages	84 pin PLCC 100 pin TQFP	84 pin PLCC 100 pin TQFP 160 pin PQFP	84 pin PLCC 160 pin PQFP 208 pin PQFP	144 pin TQFP 160 pin PQFP 208 pin PQFP 225 pin BGA	208 pin PQFP 240 pin PQFP	240 pin PQFP 304 pin PQFP

## Description

The Clear Logic CL8000 Laser-Configured ASIC (LASIC™) family offers the ultimate combination of performance, flexibility, and cost. This family is a system level second source to Altera Flex® 8000™ products. For designs not requiring in-system reprogrammability, design verification can be performed using the programmable Altera devices, and Clear Logic LASICs can be used for low cost, high volume production.

Clear Logic's innovative laser ASIC technology eliminates NRE costs, test vector development, ordering minimums and long lead times. No re-simulation or re-layout is required, as the device is engineered using a cell-based, PLD-like architecture. Clear Logic's TestCell™ technology ensures complete test coverage through the use of specialized testing modes which are transparent to the user.

The Clear Logic CL8000 Laser-Configured ASIC family is based upon a large array of logic elements. Each logic element contains a configurable look up table for combinatorial functions and a register for sequential operations. A group of eight logic elements forms a block. Laser-configured metal fuses implement logical functions and control signal routing

Laser configuration provides reduced cost and enhanced performance. These inherent performance benefits include extremely consistent propagation delays, reduced power consumption, and improved immunity to noise and upset events.

## Configuration

Clear Logic's CL8000 LASIC family is compatible with all six configuration modes defined for the Flex 8000 product family. These configuration modes include the following:

- ◆ Active Serial
- ◆ Active Parallel Up
- ◆ Active Parallel Down
- ◆ Passive Parallel Synchronous
- ◆ Passive Parallel Asynchronous
- ◆ Passive Serial

The CL8000 is already configured when it is shipped, and can be configured to bypass the FLEX 8000 configuration modes.



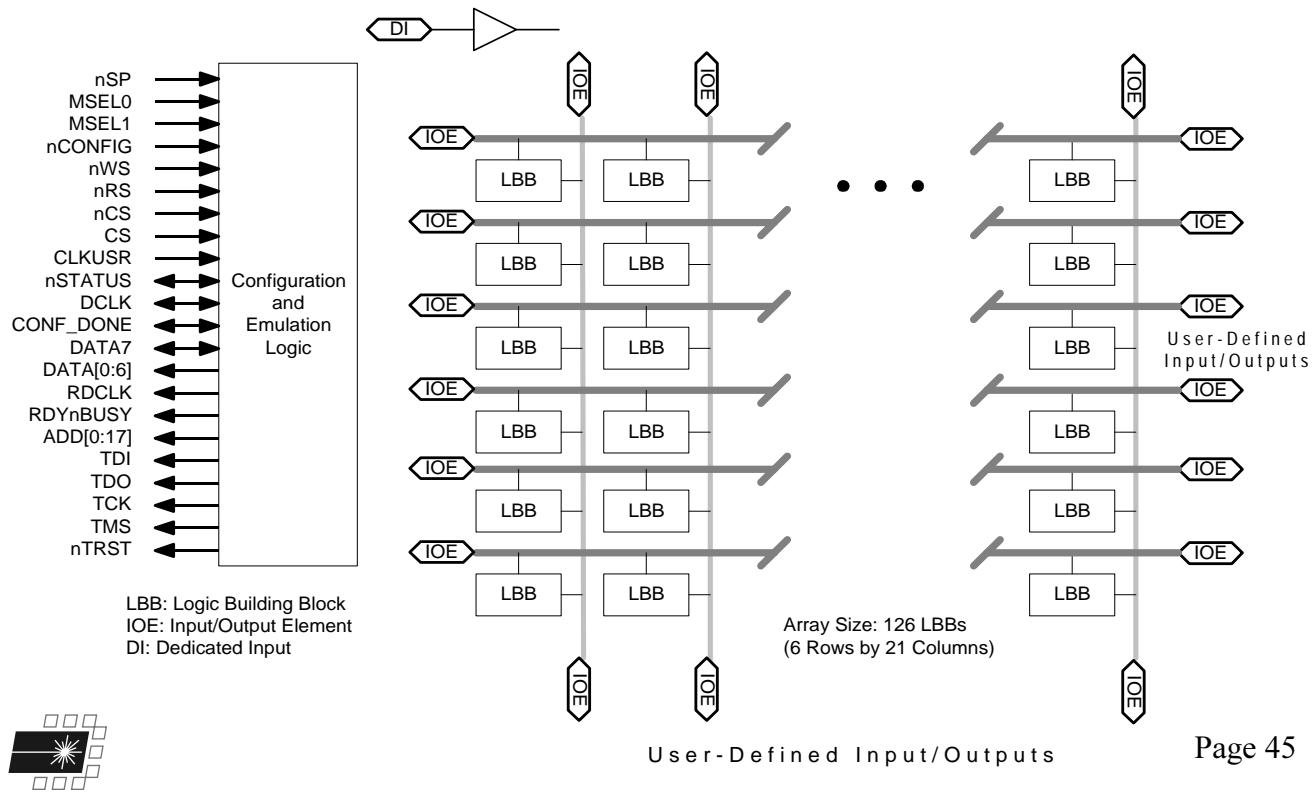
This “Instant-On” configuration mode eliminates the need for external EPROMs or microcode. In the Instant-On mode, the CL8000 device begins Initialization immediately upon a low-to-high transition on the nCONFIG pin.

## Additional Information

For further information on designing with the CL8000 LASIC family, please consult the following documents:

- ◆ *CL8K01: CL8000 Packaging Guide.* This document provides specifications and drawings for packages used by the CL8000 family.
- ◆ *CL8K02: CL8000 and System Configuration.* This document contains a detailed discussion of all aspects of configuring CL8000-based systems.
- ◆ *CL8K03: CL8000 Technology White Paper.* This document outlines the technologies employed by the CL8000 LASIC family.
- ◆ *CL8K04: Requesting a CL8000 First Article.* This document provides instructions on how to submit a bitstream file for generation of first articles.
- ◆ *CL8K05: Calculating CL8000 Power Consumption.* This document provides guidelines for calculating power consumption based on design characteristics.

## Block Diagram



## Pin Configuration

Pin Name	208 pin PQFP	240 pin PQFP
nSP	5	237
MSEL0	21	21
MSEL1	33	40
nSTATUS	124	141
nCONFIG	107	117
DCLK	154	184
CONF_DONE	138	160
nWS	118	133
nRS	121	137
RDCLK	137	158
nCS	142	166
CS	144	169
RDYnBUSY	128	146
CLKUSR	134	155
ADD17	46	58
ADD16	45	56
ADD15	44	54
ADD14	39	47
ADD13	37	45
ADD12	36	43
ADD11	31	36
ADD10	30	34
ADD9	29	32
ADD8	26	29
ADD7	25	27
ADD6	24	25
ADD5	18	18
ADD4	17	16
ADD3	16	14
ADD2	10	7
ADD1	9	5
ADD0	8	3
DATA7	177	205
DATA6	175	203
DATA5	172	200
DATA4	170	198
DATA3	168	196
DATA2	166	194
DATA1	163	191
DATA0	161	189
TDI	-	-
TDO	-	-
TCLK	-	-
TMS	-	-
nTRST	-	-
Dedicated Inputs	13, 41, 116, 146	10, 51, 130, 171
VCCINT	4, 20, 35, 48, 50, 102, 114, 131, 147	20, 42, 64, 66, 114, 128, 150, 172, 236
VCCIO	3, 19, 34, 49, 69, 87, 106, 123, 140, 156, 174, 192	19, 41, 65, 81, 99, 116, 140, 162, 186, 202, 220, 235
GND	11, 12, 27, 28, 42, 43, 60, 78, 96, 105, 115, 122, 132, 139, 148, 155, 159, 165, 183, 201	8, 9, 30, 31, 52, 53, 72, 90, 108, 115, 129, 139, 151, 161, 173, 185, 187, 193, 211, 229
NC (No Connect)	1, 2, 51, 52, 53, 54, 103, 104, 157, 158, 207, 208	-
Total user I/O pins	144	180



## DC Electrical Specifications

### Absolute Maximum Ratings

Symbol	Parameter	Conditions	Min	Max	Unit
$V_{CC}$	Supply voltage		-2.0	7.0	V
$V_I$	DC input voltage <sup>[1]</sup>		-2.0	7.0	V
$I_{OUT}$	DC output current, per pin		-25	25	mA
$T_{STG}$	Storage temperature	No bias	-65	150	°C
$T_{AMB}$	Ambient temperature	Under bias	-65	135	°C
$T_J$	Junction temperature	Under bias		135	°C

### Recommended Operating Conditions<sup>[2]</sup>

Symbol	Parameter	Conditions	Min	Max	Unit
$V_{CCINT}$	Supply voltage, internal logic and input buffers				
	Commercial Grade Devices		4.75	5.25	V
	Industrial Grade Devices		4.50	5.50	
$V_{CCIO}$	DC input voltage				
	5.0 volt commercial		4.75	5.25	V
	5.0 volt industrial		4.50	5.50	
	3.3 volt operation		3.00	3.60	
$V_I$	Input voltage		0	$V_{CCINT}$	V
$V_O$	Output voltage		0	$V_{CCIO}$	V
$T_A$	Operating temperature				
	Commercial temperature range		0	70	°C
	Industrial temperature range		-40	85	
$t_R$	Input signal rise time			40	ns
$t_F$	Input signal fall time			40	ns
$t_{RVCC}$	$V_{CC}$ rise time			100	ms

### DC Electrical Characteristics (over the operating range)

Symbol	Parameter	Conditions	Min	Typ <sup>[3]</sup>	Max	Unit
$V_{IH}$	Input HIGH Voltage		2.0	$V_{CCINT} + 0.3$	V	
$V_{IL}$	Input LOW Voltage		-0.3	0.8	V	
$V_{OH}$	Output HIGH Voltage	$I_{OH} = -4.0 \text{ mA}, V_{CCIO} = V_{CCIO[MIN]}$	2.4		V	
$V_{OL}$	Output LOW Voltage	$I_{OL} = 12.0 \text{ mA}, V_{CCIO} = V_{CCIO[MIN]}$		0.45	V	
$I_{IN}$	Input Leakage Current	$V_I = V_{CC}$ or GND	-10	10	$\mu\text{A}$	
$I_{OZ}$	Output Leakage Current	$V_I = V_{CC}$ or GND	-40	40	$\mu\text{A}$	
$I_{CC0}$	Standby Current	$V_I = \text{GND}$ , no load		0.5	10	mA



**Capacitance<sup>[4]</sup>**

Symbol	Parameter	Conditions	Min	Max	Unit
$C_{IN}$	Input Capacitance	$V_{IN} = 0 \text{ V}, f = 1.0 \text{ MHz}$		10	pF
$C_{OUT}$	Output Capacitance	$V_{OUT} = 0 \text{ V}, f = 1.0 \text{ MHz}$		10	pF

**AC Electrical Specifications****I/O Element Timing Parameters<sup>[5]</sup>**

speed: -2 speed: -3 speed: -4

Symbol	Parameter	Conditions	Min	Max	Min	Max	Min	Max	Unit
$t_{IOD}$	IOE register data delay		0.7		0.8		0.9		ns
$t_{IOC}$	IOE register control signal delay		1.7		1.8		1.9		ns
$t_{IOE}$	Output enable delay		1.7		1.8		1.9		ns
$t_{IOCO}$	IOE register clock to output delay		1.0		1.0		1.0		ns
$t_{IOCOMB}$	IOE combinatorial delay		0.3		0.2		0.1		ns
$t_{IOSU}$	IOE register setup time before clock		1.4		1.6		1.8		ns
$t_{IOH}$	IOE register hold time after clock		0.0		0.0		0.0		ns
$t_{IOCLR}$	IOE register clear delay		1.2		1.2		1.2		ns
$t_{IN}$	Input pad and buffer delay		1.5		1.6		1.7		ns
$t_{OD1}$	Output buffer and pad delay	slow slew rate = off, $V_{CCIO} = 5.0\text{v}$ , $C_L = 35 \text{ pF}$	1.1		1.4		1.7		ns
$t_{OD2}$	Output buffer and pad delay	slow slew rate = off, $V_{CCIO} = 3.3\text{v}$ , $C_L = 35 \text{ pF}$	1.6		1.9		2.2		ns
$t_{OD3}$	Output buffer and pad delay	slow slew rate = on, $C_L = 35 \text{ pF}$ , $V_{CCIO} = 3.3\text{v}$ or $5.0\text{v}$	4.6		4.9		5.2		ns
$t_{zx}$	Output buffer disable delay	$C_L = 5 \text{ pF}$	1.4		1.6		1.8		ns
$t_{zx1}$	Output buffer disable delay	slow slew rate = off, $V_{CCIO} = 5.0\text{v}$ , $C_L = 35 \text{ pF}$	1.4		1.6		1.8		ns
$t_{zx2}$	Output buffer disable delay	slow slew rate = off, $V_{CCIO} = 3.3\text{v}$ , $C_L = 35 \text{ pF}$	1.9		2.1		2.3		ns
$t_{zx3}$	Output buffer disable delay	slow slew rate = on, $C_L = 35 \text{ pF}$ , $V_{CCIO} = 3.3\text{v}$ or $5.0\text{v}$	4.9		5.1		5.3		ns

**External Timing Parameters<sup>[4]</sup>**

speed: -2 speed: -3 speed: -4

Symbol	Parameter	Conditions	Min	Max	Min	Max	Min	Max	Unit
$t_{DRR}$	Register to register delay via four LEs, three row interconnects, and four local interconnects		16		20		25		ns
$t_{ODH}$	Output data hold time after clock		1.0		1.0		1.0		ns



**Logic Element Timing Parameters<sup>[5]</sup>**

speed: -2 speed: -3 speed: -4

Symbol	Parameter	Conditions	Min	Max	Min	Max	Min	Max	Unit
$t_{LUT}$	Look up table delay for data-in		2.0		2.5		3.2		ns
$t_{CLUT}$	Look up table delay for carry-in		0.0		0.0		0.0		ns
$t_{RLUT}$	Look up table delay for LE register feedback		0.9		1.1		1.5		ns
$t_{GATE}$	Cascade gate delay		0.0		0.0		0.0		ns
$t_{CASC}$	Cascade chain routing delay		0.6		0.7		0.9		ns
$t_{CICO}$	Carry-in to carry-out delay		0.4		0.5		0.6		ns
$t_{CGEN}$	Data-in to carry-out delay		0.4		0.5		0.7		ns
$t_{CGENR}$	LE register feedback to carry-out delay		0.9		1.1		1.5		ns
$t_c$	LE register control signal delay		1.6		2.0		2.5		ns
$t_{CH}$	Clock high time		1.7		1.7		2.7		ns
$t_{CL}$	Clock low time		1.7		1.7		2.7		ns
$t_{CO}$	LE register clock-to-output delay		0.4		0.5		0.6		ns
$t_{COMB}$	Combinatorial delay		0.4		0.5		0.6		ns
$t_{SU}$	LE register setup time before clock		0.8		1.1		1.2		ns
$t_h$	LE register hold time after clock		0.9		1.1		1.5		ns
$t_{PRE}$	LE register preset delay		0.6		0.7		0.8		ns
$t_{CLR}$	LE register clear delay		0.6		0.7		0.8		ns

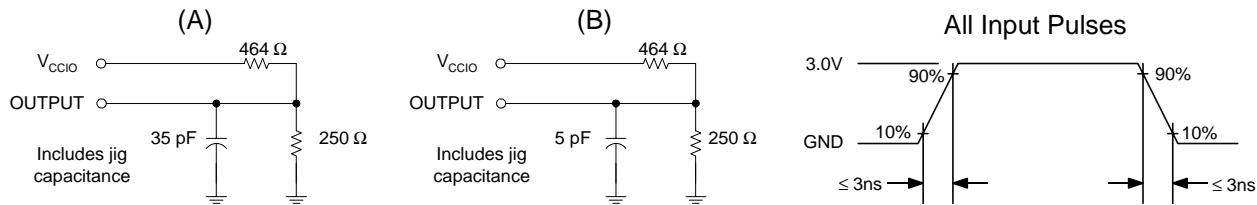
**Interconnect Timing Parameters<sup>[5]</sup>**

speed: -2 speed: -3 speed: -4

Symbol	Parameter	Conditions	Min	Max	Min	Max	Min	Max	Unit
$t_{LABCASC}$	Cascade delay between LEs in different LABs		0.3		0.3		0.4		ns
$t_{LABCARRY}$	Carry delay between LEs in different LABs		0.3		0.3		0.4		ns
$t_{LOCAL}$	LAB local interconnect delay		0.5		0.6		0.8		ns
$t_{ROW}$	Row interconnect routing delay		5.0		5.0		5.0		ns
$t_{COL}$	Column interconnect routing delay		3.0		3.0		3.0		ns
$t_{DIN_C}$	Dedicated input to LE control delay		5.0		5.0		5.5		ns
$t_{DIN_D}$	Dedicated input to LE data delay		7.0		7.0		7.5		ns
$t_{DIN_IO}$	Dedicated input to IOE control delay		5.0		5.0		5.5		ns



## AC Test Conditions



## Notes to Tables

- During transitions, inputs may undershoot to -2.0v for periods shorter than 20ns. Otherwise, minimum DC input voltage is 0.3v.
- The following devices do not have  $V_{CCIO}$  pins: CL8282A, CL8452A. For these devices, all references to  $V_{CCIO}$  should be changed to  $V_{CCINT}$ .
- Typical values are at  $V_{CC}$  of 5.0 volts and ambient temperature of 25 °C.
- Guaranteed but not tested. Characterized initially, and after any design changes which may affect these parameters.
- Internal timing delays are based on characterization, and cannot be explicitly tested. Internal timing parameters should be used for performance estimation only.

## Ordering Information

Part Number	Temperature Range	Package Type	Speed	Altera Equivalent
CL81188AQC208-4	Commercial	208-pin Plastic QFP	-4 (slowest)	EPF81188AQC208-4
CL81188AQC208-3			-3	EPF81188AQC208-3
CL81188AQC208-2			-2 (fastest)	EPF81188AQC208-2
CL81188AQC240-4		240-pin Plastic QFP	-4 (slowest)	EPF81188AQC240-4
CL81188AQC240-3			-3	EPF81188AQC240-3
CL81188AQC240-2			-2 (fastest)	EPF81188AQC240-2
CL81188AQI208-4	Industrial	208-pin Plastic QFP	-4 (slowest)	EPF81188AQI208-4
CL81188AQI208-3			-3 (fastest)	EPF81188AQI208-3
CL81188AQI240-4		240-pin Plastic QFP	-4	EPF81188ARI240-4

